Sumitomo G600 Mold compound – Mini SO

Reliability Data for Mini SO Package at Carsem-M using Ablestik 84-1LMISR4 Die Attach and Sumitomo G600 Molding compound

Test	Conditions	Sample Size	Results
Autoclave*#	JEDEC-STD-22-Method A102	1*82	Pass
Autoclave*	JEDEC-STD-22-Method A102	3*82	Pass
Autoclave*	JEDEC-STD-22-Method A102	1*82	Pass
Autoclave*#	JEDEC-STD-22-Method A102	2*82	Pass
Highly Accelerated Stress Test (HAST)*#	JEDEC-STD-22-Method A110	1*82	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC-STD-22-Method A110	6*82	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC-STD-22-Method A110	3*82	Pass
Temperature Cycling*	JEDEC-STD-22, Method A104	3*82	Pass
Temperature Cycling*#	JEDEC-STD-22, Method A104	1*82	Pass
Temperature Cycling*	JEDEC-STD-22, Method A104	1*82	Pass
Temperature Cycling*	JEDEC-STD-22, Method A104	3*82	Pass
Temperature Cycling*	JEDEC-STD-22, Method A104	3*82	Pass
High Temperature Storage Life (HTSL)	JESD22-A103	3*82	Pass
High Temperature Storage Life (HTSL)	JESD22-A103	3*77	Pass
High Temperature Storage Life (HTSL)	JESD22-A103	1*77	Pass
High Temperature Storage Life (HTSL)	JESD22-A103	1*77	Pass
High Temperature Storage Life (HTSL)	JESD22-A103	1*50	Pass

*Preconditioned Per JEDEC/IPC J-STD-020

Tested post stress at hot temp.